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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

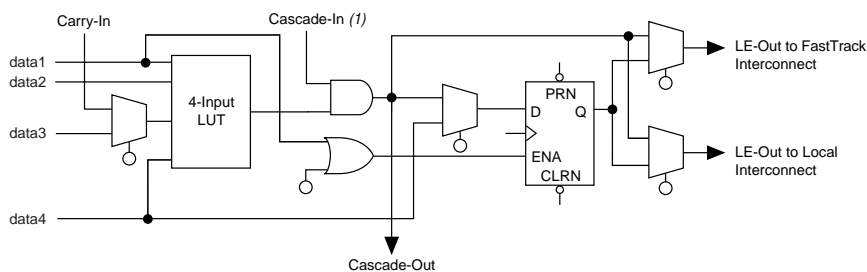
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

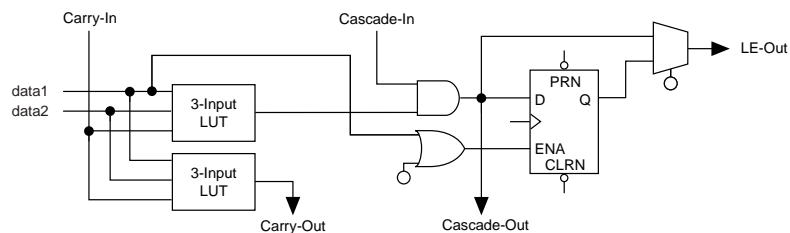
Product Status	Obsolete
Number of LABs/CLBs	624
Number of Logic Elements/Cells	4992
Total RAM Bits	24576
Number of I/O	189
Number of Gates	158000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	240-BFQFP Exposed Pad
Supplier Device Package	240-RQFP (32x32)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epf10k100arc240-3">https://www.e-xfl.com/product-detail/intel/epf10k100arc240-3</a>

**Figure 9. FLEX 10K LE Operating Modes**

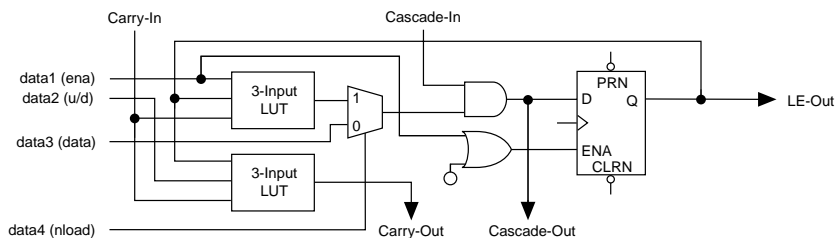
**Normal Mode**



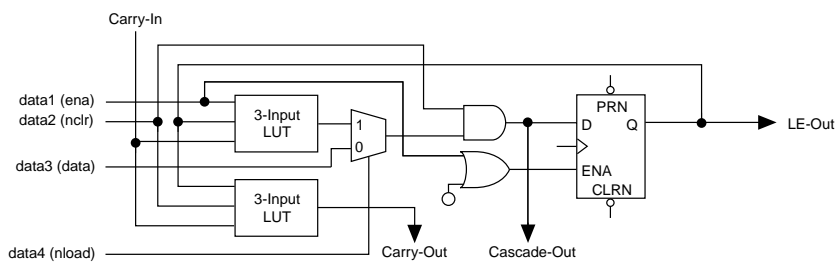
**Arithmetic Mode**



**Up/Down Counter Mode**



**Clearable Counter Mode**



**Note:**

(1) Packed registers cannot be used with the cascade chain.

### Normal Mode

The normal mode is suitable for general logic applications and wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a four-input LUT. The Compiler automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. Either the register or the LUT can be used to drive both the local interconnect and the FastTrack Interconnect at the same time.

The LUT and the register in the LE can be used independently; this feature is known as register packing. To support register packing, the LE has two outputs; one drives the local interconnect and the other drives the FastTrack Interconnect. The DATA4 signal can drive the register directly, allowing the LUT to compute a function that is independent of the registered signal; a three-input function can be computed in the LUT, and a fourth independent signal can be registered. Alternatively, a four-input function can be generated, and one of the inputs to this function can be used to drive the register. The register in a packed LE can still use the clock enable, clear, and preset signals in the LE. In a packed LE, the register can drive the FastTrack Interconnect while the LUT drives the local interconnect, or vice versa.

### Arithmetic Mode

The arithmetic mode offers 2 three-input LUTs that are ideal for implementing adders, accumulators, and comparators. One LUT computes a three-input function, and the other generates a carry output. As shown in [Figure 9](#) on page 19, the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, in an adder, this output is the sum of three signals: a, b, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain.

### **Asynchronous Preset**

An asynchronous preset is implemented as either an asynchronous load, or with an asynchronous clear. If DATA3 is tied to  $V_{CC}$ , asserting LABCTRL1 asynchronously loads a one into the register. Alternatively, the Altera software can provide preset control by using the clear and inverting the input and output of the register. Inversion control is available for the inputs to both LEs and IOEs. Therefore, if a register is preset by only one of the two LABCTRL signals, the DATA3 input is not needed and can be used for one of the LE operating modes.

### **Asynchronous Preset & Clear**

When implementing asynchronous clear and preset, LABCTRL1 controls the preset and LABCTRL2 controls the clear. DATA3 is tied to  $V_{CC}$ , therefore, asserting LABCTRL1 asynchronously loads a one into the register, effectively presetting the register. Asserting LABCTRL2 clears the register.

### **Asynchronous Load with Clear**

When implementing an asynchronous load in conjunction with the clear, LABCTRL1 implements the asynchronous load of DATA3 by controlling the register preset and clear. LABCTRL2 implements the clear by controlling the register clear; LABCTRL2 does not have to feed the preset circuits.

### **Asynchronous Load with Preset**

When implementing an asynchronous load in conjunction with preset, the Altera software provides preset control by using the clear and inverting the input and output of the register. Asserting LABCTRL2 presets the register, while asserting LABCTRL1 loads the register. The Altera software inverts the signal that drives DATA3 to account for the inversion of the register's output.

### **Asynchronous Load without Preset or Clear**

When implementing an asynchronous load without preset or clear, LABCTRL1 implements the asynchronous load of DATA3 by controlling the register preset and clear.

## FastTrack Interconnect

In the FLEX 10K architecture, connections between LEs and device I/O pins are provided by the FastTrack Interconnect, which is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. Each row of LABs is served by a dedicated row interconnect. The row interconnect can drive I/O pins and feed other LABs in the device. The column interconnect routes signals between rows and can drive I/O pins.

A row channel can be driven by an LE or by one of three column channels. These four signals feed dual 4-to-1 multiplexers that connect to two specific row channels. These multiplexers, which are connected to each LE, allow column channels to drive row channels even when all eight LEs in an LAB drive the row interconnect.

Each column of LABs is served by a dedicated column interconnect. The column interconnect can then drive I/O pins or another row's interconnect to route the signals to other LABs in the device. A signal from the column interconnect, which can be either the output of an LE or an input from an I/O pin, must be routed to the row interconnect before it can enter an LAB or EAB. Each row channel that is driven by an IOE or EAB can drive one specific column channel.

Access to row and column channels can be switched between LEs in adjacent pairs of LABs. For example, an LE in one LAB can drive the row and column channels normally driven by a particular LE in the adjacent LAB in the same row, and vice versa. This routing flexibility enables routing resources to be used more efficiently. See [Figure 11](#).

For improved routing, the row interconnect is comprised of a combination of full-length and half-length channels. The full-length channels connect to all LABs in a row; the half-length channels connect to the LABs in half of the row. The EAB can be driven by the half-length channels in the left half of the row and by the full-length channels. The EAB drives out to the full-length channels. In addition to providing a predictable, row-wide interconnect, this architecture provides increased routing resources. Two neighboring LABs can be connected using a half-row channel, thereby saving the other half of the channel for the other half of the row.

Table 7 summarizes the FastTrack Interconnect resources available in each FLEX 10K device.

<b>Table 7. FLEX 10K FastTrack Interconnect Resources</b>				
<b>Device</b>	<b>Rows</b>	<b>Channels per Row</b>	<b>Columns</b>	<b>Channels per Column</b>
EPF10K10 EPF10K10A	3	144	24	24
EPF10K20	6	144	24	24
EPF10K30 EPF10K30A	6	216	36	24
EPF10K40	8	216	36	24
EPF10K50 EPF10K50V	10	216	36	24
EPF10K70	9	312	52	24
EPF10K100 EPF10K100A	12	312	52	24
EPF10K130V	16	312	52	32
EPF10K250A	20	456	76	40

In addition to general-purpose I/O pins, FLEX 10K devices have six dedicated input pins that provide low-skew signal distribution across the device. These six inputs can be used for global clock, clear, preset, and peripheral output enable and clock enable control signals. These signals are available as control signals for all LABs and IOEs in the device.

The dedicated inputs can also be used as general-purpose data inputs because they can feed the local interconnect of each LAB in the device. However, the use of dedicated inputs as data inputs can introduce additional delay into the control signal network.

Each IOE selects the clock, clear, clock enable, and output enable controls from a network of I/O control signals called the peripheral control bus. The peripheral control bus uses high-speed drivers to minimize signal skew across devices; it provides up to 12 peripheral control signals that can be allocated as follows:

- Up to eight output enable signals
- Up to six clock enable signals
- Up to two clock signals
- Up to two clear signals

If more than six clock enable or eight output enable signals are required, each IOE on the device can be controlled by clock enable and output enable signals driven by specific LEs. In addition to the two clock signals available on the peripheral control bus, each IOE can use one of two dedicated clock pins. Each peripheral control signal can be driven by any of the dedicated input pins or the first LE of each LAB in a particular row. In addition, an LE in a different row can drive a column interconnect, which causes a row interconnect to drive the peripheral control signal. The chip-wide reset signal will reset all IOE registers, overriding any other control signals.

Tables 8 and 9 list the sources for each peripheral control signal, and the rows that can drive global signals. These tables also show how the output enable, clock enable, clock, and clear signals share 12 peripheral control signals.

**Figure 15. FLEX 10K Column-to-IOE Connections**

The values for  $m$  and  $n$  are provided in Table 11.

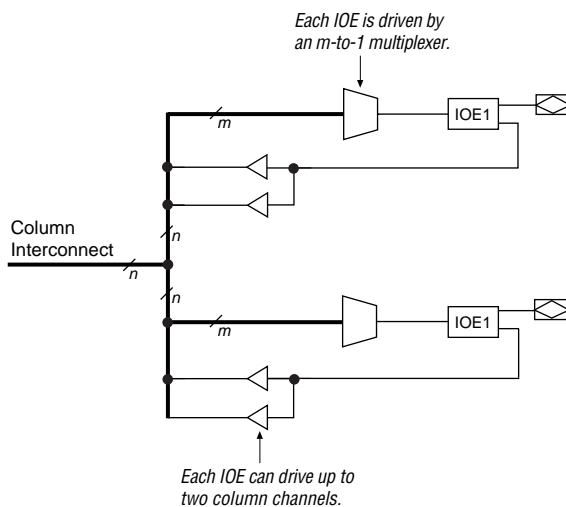


Table 11 lists the FLEX 10K column-to-IOE interconnect resources.

**Table 11. FLEX 10K Column-to-IOE Interconnect Resources**

Device	Channels per Column ( $n$ )	Column Channel per Pin ( $m$ )
EPF10K10 EPF10K10A	24	16
EPF10K20	24	16
EPF10K30 EPF10K30A	24	16
EPF10K40	24	16
EPF10K50 EPF10K50V	24	16
EPF10K70	24	16
EPF10K100 EPF10K100A	24	16
EPF10K130V	32	24
EPF10K250A	40	32



## ClockLock & ClockBoost Features

To support high-speed designs, selected FLEX 10K devices offer optional ClockLock and ClockBoost circuitry containing a phase-locked loop (PLL) that is used to increase design speed and reduce resource usage. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost feature allows the designer to distribute a low-speed clock and multiply that clock on-device. Combined, the ClockLock and ClockBoost features provide significant improvements in system performance and bandwidth.

The ClockLock and ClockBoost features in FLEX 10K devices are enabled through the Altera software. External devices are not required to use these features. The output of the ClockLock and ClockBoost circuits is not available at any of the device pins.

The ClockLock and ClockBoost circuitry locks onto the rising edge of the incoming clock. The circuit output can only drive the clock inputs of registers; the generated clock cannot be gated or inverted.

The dedicated clock pin (GCLK1) supplies the clock to the ClockLock and ClockBoost circuitry. When the dedicated clock pin is driving the ClockLock or ClockBoost circuitry, it cannot drive elsewhere in the device.

In designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to GCLK1. With the Altera software, GCLK1 can feed both the ClockLock and ClockBoost circuitry in the FLEX 10K device. However, when both circuits are used, the other clock pin (GCLK0) cannot be used. [Figure 17](#) shows a block diagram of how to enable both the ClockLock and ClockBoost circuits in the Altera software. The example shown is a schematic, but a similar approach applies for designs created in AHDL, VHDL, and Verilog HDL. When the ClockLock and ClockBoost circuits are used simultaneously, the input frequency parameter must be the same for both circuits. In [Figure 17](#), the input frequency must meet the requirements specified when the ClockBoost multiplication factor is two.

Table 12 describes the FLEX 10K device supply voltages and MultiVolt I/O support levels.

**Table 12. Supply Voltages & MultiVolt I/O Support Levels**

Devices	Supply Voltage (V)		MultiVolt I/O Support Levels (V)	
	V <sub>CCINT</sub>	V <sub>CCIO</sub>	Input	Output
FLEX 10K (1)	5.0	5.0	3.3 or 5.0	5.0
	5.0	3.3	3.3 or 5.0	3.3 or 5.0
EPF10K50V (1)	3.3	3.3	3.3 or 5.0	3.3 or 5.0
EPF10K130V	3.3	3.3	3.3 or 5.0	3.3 or 5.0
FLEX 10KA (1)	3.3	3.3	2.5, 3.3, or 5.0	3.3 or 5.0
	3.3	2.5	2.5, 3.3, or 5.0	2.5

**Note**

(1) 240-pin QFP packages do not support the MultiVolt I/O features, so they do not have separate V<sub>CCIO</sub> pins.

## Power Sequencing & Hot-Socketing

Because FLEX 10K devices can be used in a multi-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V<sub>CCIO</sub> and V<sub>CCINT</sub> power supplies can be powered in any order.

Signals can be driven into FLEX 10KA devices before and during power up without damaging the device. Additionally, FLEX 10KA devices do not drive out during power up. Once operating conditions are reached, FLEX 10KA devices operate as specified by the user.

## IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All FLEX 10K devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1-1990 specification. All FLEX 10K devices can also be configured using the JTAG pins through the BitBlaster serial download cable, or ByteBlasterMV parallel port download cable, or via hardware that uses the Jam™ programming and test language. JTAG BST can be performed before or after configuration, but not during configuration. FLEX 10K devices support the JTAG instructions shown in Table 13.

**Table 52. EPF10K30 Device Interconnect Timing Microparameters** *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
$t_{DIN2IOE}$		6.9		8.7	ns
$t_{DIN2LE}$		3.6		4.8	ns
$t_{DIN2DATA}$		5.5		7.2	ns
$t_{DCLK2IOE}$		4.6		6.2	ns
$t_{DCLK2LE}$		3.6		4.8	ns
$t_{SAMELAB}$		0.3		0.3	ns
$t_{SAMEROW}$		3.3		3.7	ns
$t_{SAMECOLUMN}$		2.5		2.7	ns
$t_{DIFFROW}$		5.8		6.4	ns
$t_{TROWROWS}$		9.1		10.1	ns
$t_{LEPERIPH}$		6.2		7.1	ns
$t_{LABCARRY}$		0.4		0.6	ns
$t_{LABCASC}$		2.4		3.0	ns

**Table 53. EPF10K40 Device Interconnect Timing Microparameters** *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
$t_{DIN2IOE}$		7.6		9.4	ns
$t_{DIN2LE}$		3.6		4.8	ns
$t_{DIN2DATA}$		5.5		7.2	ns
$t_{DCLK2IOE}$		4.6		6.2	ns
$t_{DCLK2LE}$		3.6		4.8	ns
$t_{SAMELAB}$		0.3		0.3	ns
$t_{SAMEROW}$		3.3		3.7	ns
$t_{SAMECOLUMN}$		3.1		3.2	ns
$t_{DIFFROW}$		6.4		6.4	ns
$t_{TROWROWS}$		9.7		10.6	ns
$t_{LEPERIPH}$		6.4		7.1	ns
$t_{LABCARRY}$		0.4		0.6	ns
$t_{LABCASC}$		2.4		3.0	ns

**Table 60. EPF10K70 Device EAB Internal Timing Macroparameters** *Note (1)*

Symbol	-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{EABAA}$		12.1		13.7		17.0	ns
$t_{EABRCCOMB}$	12.1		13.7		17.0		ns
$t_{EABRCREG}$	8.6		9.7		11.9		ns
$t_{EABWP}$	5.2		5.8		7.2		ns
$t_{EABWCCOMB}$	6.5		7.3		9.0		ns
$t_{EABWCREG}$	11.6		13.0		16.0		ns
$t_{EABDD}$		8.8		10.0		12.5	ns
$t_{EABDATA CO}$		1.7		2.0		3.4	ns
$t_{EABDATASU}$	4.7		5.3		5.6		ns
$t_{EABDATAH}$	0.0		0.0		0.0		ns
$t_{EABWESU}$	4.9		5.5		5.8		ns
$t_{EABWEH}$	0.0		0.0		0.0		ns
$t_{EABWDSU}$	1.8		2.1		2.7		ns
$t_{EABWDH}$	0.0		0.0		0.0		ns
$t_{EABWASU}$	4.1		4.7		5.8		ns
$t_{EABWAH}$	0.0		0.0		0.0		ns
$t_{EABWO}$		8.4		9.5		11.8	ns

**Table 69. EPF10K100 Device External Timing Parameters** *Note (1)*

Symbol	-3DX Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{DDR}}$		19.1		19.1		24.2	ns
$t_{\text{INSU}}$ (2), (3), (4)	7.8		7.8		8.5		ns
$t_{\text{OUTCO}}$ (3), (4)	2.0	11.1	2.0	11.1	2.0	14.3	ns
$t_{\text{INH}}$ (3)	0.0		0.0		0.0		ns
$t_{\text{INSU}}$ (2), (3), (5)	6.2		–		–		ns
$t_{\text{OUTCO}}$ (3), (5)	2.0	6.7		–		–	ns

**Table 70. EPF10K100 Device External Bidirectional Timing Parameters** *Note (1)*

Symbol	-3DX Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$ (4)	8.1		8.1		10.4		ns
$t_{\text{INHBIDIR}}$ (4)	0.0		0.0		0.0		ns
$t_{\text{OUTCOBIDIR}}$ (4)	2.0	11.1	2.0	11.1	2.0	14.3	ns
$t_{\text{XZBIDIR}}$ (4)		15.3		15.3		18.4	ns
$t_{\text{ZXBIDIR}}$ (4)		15.3		15.3		18.4	ns
$t_{\text{INSUBIDIR}}$ (5)	9.1		–		–		ns
$t_{\text{INHBIDIR}}$ (5)	0.0		–		–		ns
$t_{\text{OUTCOBIDIR}}$ (5)	2.0	7.2	–	–	–	–	ns
$t_{\text{XZBIDIR}}$ (5)		14.3		–		–	ns
$t_{\text{ZXBIDIR}}$ (5)		14.3		–		–	ns

**Notes to tables:**

- (1) All timing parameters are described in Tables 32 through 38 in this data sheet.
- (2) Using an LE to register the signal may provide a lower setup time.
- (3) This parameter is specified by characterization.
- (4) This parameter is measured without the use of the ClockLock or ClockBoost circuits.
- (5) This parameter is measured with the use of the ClockLock or ClockBoost circuits.

**Table 75. EPF10K50V Device Interconnect Timing Microparameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		4.7		6.0		7.1		8.2	ns
$t_{DIN2LE}$		2.5		2.6		3.1		3.9	ns
$t_{DIN2DATA}$		4.4		5.9		6.8		7.7	ns
$t_{DCLK2IOE}$		2.5		3.9		4.7		5.5	ns
$t_{DCLK2LE}$		2.5		2.6		3.1		3.9	ns
$t_{SAMELAB}$		0.2		0.2		0.3		0.3	ns
$t_{SAMEROW}$		2.8		3.0		3.2		3.4	ns
$t_{SAMECOLUMN}$		3.0		3.2		3.4		3.6	ns
$t_{DIFFROW}$		5.8		6.2		6.6		7.0	ns
$t_{TWOROWS}$		8.6		9.2		9.8		10.4	ns
$t_{LEPERIPH}$		4.5		5.5		6.1		7.0	ns
$t_{LABCARRY}$		0.3		0.4		0.5		0.7	ns
$t_{LABCASC}$		0.0		1.3		1.6		2.0	ns

**Table 76. EPF10K50V Device External Timing Parameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{DRR}$		11.2		14.0		17.2		21.1	ns
$t_{INSU}$ (2), (3)	5.5		4.2		5.2		6.9		ns
$t_{INH}$ (3)	0.0		0.0		0.0		0.0		ns
$t_{OUTCO}$ (3)	2.0	5.9	2.0	7.8	2.0	9.5	2.0	11.1	ns

**Table 77. EPF10K50V Device External Bidirectional Timing Parameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{INSUBIDIR}$	2.0		2.8		3.5		4.1		ns
$t_{INHBIDIR}$	0.0		0.0		0.0		0.0		ns
$t_{OUTCOBIDIR}$	2.0	5.9	2.0	7.8	2.0	9.5	2.0	11.1	ns
$t_{XZBIDIR}$		8.0		9.8		11.8		14.3	ns
$t_{ZXBIDIR}$		8.0		9.8		11.8		14.3	ns

**Table 82. EPF10K130V Device Interconnect Timing Microparameters** *Note (1)*

Symbol	-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		8.0		9.0		9.5	ns
$t_{DIN2LE}$		2.4		3.0		3.1	ns
$t_{DIN2DATA}$		5.0		6.3		7.4	ns
$t_{DCLK2IOE}$		3.6		4.6		5.1	ns
$t_{DCLK2LE}$		2.4		3.0		3.1	ns
$t_{SAMELAB}$		0.4		0.6		0.8	ns
$t_{SAMEROW}$		4.5		5.3		6.5	ns
$t_{SAMECOLUMN}$		9.0		9.5		9.7	ns
$t_{DIFFROW}$		13.5		14.8		16.2	ns
$t_{TWOROWS}$		18.0		20.1		22.7	ns
$t_{LEPERIPH}$		8.1		8.6		9.5	ns
$t_{LABCARRY}$		0.6		0.8		1.0	ns
$t_{LABCASC}$		0.8		1.0		1.2	ns

**Table 83. EPF10K130V Device External Timing Parameters** *Note (1)*

Symbol	-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{DRR}$		15.0		19.1		24.2	ns
$t_{INSU}$ (2), (3)	6.9		8.6		11.0		ns
$t_{INH}$ (3)	0.0		0.0		0.0		ns
$t_{OUTCO}$ (3)	2.0	7.8	2.0	9.9	2.0	11.3	ns

**Table 84. EPF10K130V Device External Bidirectional Timing Parameters** *Note (1)*

Symbol	-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSUBIDIR}$	6.7		8.5		10.8		ns
$t_{INHBIDIR}$	0.0		0.0		0.0		ns
$t_{OUTCOBIDIR}$	2.0	6.9	2.0	8.8	2.0	10.2	ns
$t_{XZBIDIR}$		12.9		16.4		19.3	ns
$t_{ZXBIDIR}$		12.9		16.4		19.3	ns

**Table 86. EPF10K10A Device IOE Timing Microparameters** *Note (1) (Part 2 of 2)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{IOH}$	0.8		1.0		1.3		ns
$t_{IOCLR}$		1.2		1.4		1.9	ns
$t_{OD1}$		1.2		1.4		1.9	ns
$t_{OD2}$		2.9		3.5		4.7	ns
$t_{OD3}$		6.6		7.8		10.5	ns
$t_{XZ}$		1.2		1.4		1.9	ns
$t_{ZX1}$		1.2		1.4		1.9	ns
$t_{ZX2}$		2.9		3.5		4.7	ns
$t_{ZX3}$		6.6		7.8		10.5	ns
$t_{INREG}$		5.2		6.3		8.4	ns
$t_{IOFD}$		3.1		3.8		5.0	ns
$t_{INCOMB}$		3.1		3.8		5.0	ns



## Notes to tables:

- (1) All timing parameters are described in Tables 32 through 38 in this data sheet.
- (2) Using an LE to register the signal may provide a lower setup time.
- (3) This parameter is specified by characterization.

Tables 92 through 98 show EPF10K30A device internal and external timing parameters.

**Table 92. EPF10K30A Device LE Timing Microparameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		0.8		1.1		1.5	ns
$t_{CLUT}$		0.6		0.7		1.0	ns
$t_{RLUT}$		1.2		1.5		2.0	ns
$t_{PACKED}$		0.6		0.6		1.0	ns
$t_{EN}$		1.3		1.5		2.0	ns
$t_{CICO}$		0.2		0.3		0.4	ns
$t_{CGEN}$		0.8		1.0		1.3	ns
$t_{CGENR}$		0.6		0.8		1.0	ns
$t_{CASC}$		0.9		1.1		1.4	ns
$t_C$		1.1		1.3		1.7	ns
$t_{CO}$		0.4		0.6		0.7	ns
$t_{COMB}$		0.6		0.7		0.9	ns
$t_{SU}$	0.9		0.9		1.4		ns
$t_H$	1.1		1.3		1.7		ns
$t_{PRE}$		0.5		0.6		0.8	ns
$t_{CLR}$		0.5		0.6		0.8	ns
$t_{CH}$	3.0		3.5		4.0		ns
$t_{CL}$	3.0		3.5		4.0		ns

**Table 93. EPF10K30A Device IOE Timing Microparameters** *Note (1) (Part 1 of 2)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{IOD}$		2.2		2.6		3.4	ns
$t_{IOC}$		0.3		0.3		0.5	ns
$t_{IOCO}$		0.2		0.2		0.3	ns
$t_{IOCOMB}$		0.5		0.6		0.8	ns
$t_{IOSU}$	1.4		1.7		2.2		ns

**Table 95. EPF10K30A Device EAB Internal Timing Macroparameters***Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{EABAA}$		9.7		11.6		16.2	ns
$t_{EABRCCOMB}$	9.7		11.6		16.2		ns
$t_{EABRCREG}$	5.9		7.1		9.7		ns
$t_{EABWP}$	3.8		4.5		5.9		ns
$t_{EABWCCOMB}$	4.0		4.7		6.3		ns
$t_{EABWCREG}$	9.8		11.6		16.6		ns
$t_{EABDD}$		9.2		11.0		16.1	ns
$t_{EABDATACO}$		1.7		2.1		3.4	ns
$t_{EABDATASU}$	2.3		2.7		3.5		ns
$t_{EABDATAH}$	0.0		0.0		0.0		ns
$t_{EABWESU}$	3.3		3.9		4.9		ns
$t_{EABWEH}$	0.0		0.0		0.0		ns
$t_{EABWDSU}$	3.2		3.8		5.0		ns
$t_{EABWDH}$	0.0		0.0		0.0		ns
$t_{EABWASU}$	3.7		4.4		5.1		ns
$t_{EABWAH}$	0.0		0.0		0.0		ns
$t_{EABWO}$		6.1		7.3		11.3	ns

**Notes to tables:**

- (1) All timing parameters are described in Tables 32 through 38 in this data sheet.
- (2) Using an LE to register the signal may provide a lower setup time.
- (3) This parameter is specified by characterization.

Tables 99 through 105 show EPF10K100A device internal and external timing parameters.

**Table 99. EPF10K100A Device LE Timing Microparameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		1.0		1.2		1.4	ns
$t_{CLUT}$		0.8		0.9		1.1	ns
$t_{RLUT}$		1.4		1.6		1.9	ns
$t_{PACKED}$		0.4		0.5		0.5	ns
$t_{EN}$		0.6		0.7		0.8	ns
$t_{CICO}$		0.2		0.2		0.3	ns
$t_{CGEN}$		0.4		0.4		0.6	ns
$t_{CGENR}$		0.6		0.7		0.8	ns
$t_{CASC}$		0.7		0.9		1.0	ns
$t_C$		0.9		1.0		1.2	ns
$t_{CO}$		0.2		0.3		0.3	ns
$t_{COMB}$		0.6		0.7		0.8	ns
$t_{SU}$	0.8		1.0		1.2		ns
$t_H$	0.3		0.5		0.5		ns
$t_{PRE}$		0.3		0.3		0.4	ns
$t_{CLR}$		0.3		0.3		0.4	ns
$t_{CH}$	2.5		3.5		4.0		ns
$t_{CL}$	2.5		3.5		4.0		ns

## Notes to tables:

- (1) All timing parameters are described in Tables 32 through 38 in this data sheet.
- (2) Using an LE to register the signal may provide a lower setup time.
- (3) This parameter is specified by characterization.

Tables 106 through 112 show EPF10K250A device internal and external timing parameters.

Table 106. EPF10K250A Device LE Timing Microparameters <i>Note (1)</i>							
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		0.9		1.0		1.4	ns
$t_{CLUT}$		1.2		1.3		1.6	ns
$t_{RLUT}$		2.0		2.3		2.7	ns
$t_{PACKED}$		0.4		0.4		0.5	ns
$t_{EN}$		1.4		1.6		1.9	ns
$t_{CICO}$		0.2		0.3		0.3	ns
$t_{CGEN}$		0.4		0.6		0.6	ns
$t_{CGENR}$		0.8		1.0		1.1	ns
$t_{CASC}$		0.7		0.8		1.0	ns
$t_C$		1.2		1.3		1.6	ns
$t_{CO}$		0.6		0.7		0.9	ns
$t_{COMB}$		0.5		0.6		0.7	ns
$t_{SU}$	1.2		1.4		1.7		ns
$t_H$	1.2		1.3		1.6		ns
$t_{PRE}$		0.7		0.8		0.9	ns
$t_{CLR}$		0.7		0.8		0.9	ns
$t_{CH}$	2.5		3.0		3.5		ns
$t_{CL}$	2.5		3.0		3.5		ns

**Table 107. EPF10K250A Device IOE Timing Microparameters** *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{IOD}$		1.2		1.3		1.6	ns
$t_{IOC}$		0.4		0.4		0.5	ns
$t_{IOCO}$		0.8		0.9		1.1	ns
$t_{IOCOMB}$		0.7		0.7		0.8	ns
$t_{IOSU}$	2.7		3.1		3.6		ns
$t_{IOH}$	0.2		0.3		0.3		ns
$t_{IOCLR}$		1.2		1.3		1.6	ns
$t_{OD1}$		3.2		3.6		4.2	ns
$t_{OD2}$		5.9		6.7		7.8	ns
$t_{OD3}$		8.7		9.8		11.5	ns
$t_{XZ}$		3.8		4.3		5.0	ns
$t_{ZX1}$		3.8		4.3		5.0	ns
$t_{ZX2}$		6.5		7.4		8.6	ns
$t_{ZX3}$		9.3		10.5		12.3	ns
$t_{INREG}$		8.2		9.3		10.9	ns
$t_{IOFD}$		9.0		10.2		12.0	ns
$t_{INCOMB}$		9.0		10.2		12.0	ns